# Supertex inc.



# P-Channel Enhancement Mode Vertical DMOS FETs

#### **Features**

- Low threshold (-2.4V max.)
- High input impedance
- Low input capacitance (125pF max.)
- Fast switching speeds
- Low on-resistance
- Free from secondary breakdown
- Low input and output leakage

## Applications

- Logic level interfaces ideal for TTL and CMOS
- Solid state relays
- Battery operated systems
- Photo voltaic drives
- Analog switches
- General purpose line drivers
- Telecom switches

## **General Description**

This low threshold enhancement-mode (normally-off) transistor utilizes a vertical DMOS structure and Supertex's well-proven silicon-gate manufacturing process. This combination produces a device with the power handling capabilities of bipolar transistors and with the high input impedance and positive temperature coefficient inherent in MOS devices. Characteristic of all MOS structures, this device is free from thermal runaway and thermally-induced secondary breakdown.

Supertex's vertical DMOS FETs are ideally suited to a wide range of switching and amplifying applications where very low threshold voltage, high breakdown voltage, high input impedance, low input capacitance, and fast switching speeds are desired.

## Ordering Information

	Package Options		BV <sub>pss</sub> /BV <sub>pcs</sub>	$R_{DS(ON)}$	$V_{GS(th)}$	I <sub>D(ON)</sub>	
TO-92	TO-243AA (SOT-89)	Die*	(V)	(max) (Ω)	(max) (V)	(min) (A)	
TP2540N3-G	TP2540N8-G	TP2540ND	-400	25	-2.4	-0.4	
-		TO-92 TO-243AA (SOT-89)	TO-92 TO-243AA (SOT-89) Die*	TO-92 TO-243AA (SOT-89) Die* (V)	TO-92 TO-243AA (SOT-89) Die* BV <sub>DSS</sub> /BV <sub>DGS</sub> N <sub>DS(ON)</sub> (max) (Ω)	Package Options BV <sub>DSS</sub> /BV <sub>DGS</sub> N <sub>DS(ON)</sub> V <sub>GS(th)</sub> TO-92 TO-243AA (SOT-89) Die* (V) (max) (max)	

-G indicates package is RoHS compliant ('Green',



# Pin Configurations



## **Absolute Maximum Ratings**

Parameter	Value
Drain-to-source voltage	BV <sub>DSS</sub>
Drain-to-gate voltage	BV <sub>DGS</sub>
Gate-to-source voltage	±20V
Operating and storage temperature	-55°C to +150°C
Soldering temperature*	+300°C

Absolute Maximum Ratings are those values beyond which damage to the device may occur. Functional operation under these conditions is not implied. Continuous operation of the device at the absolute rating level may affect device reliability. All voltages are referenced to device ground.

\* Distance of 1.6mm from case for 10 seconds.

## **Thermal Characteristics**

Package	I <sub>D</sub> (continuous)⁺ (mA)	l <sub>D</sub> (pulsed) (A)	Power Dissipation @ T <sub>A</sub> = 25°C (W)	<i>θ<sub>jc</sub></i> °C/W	θ <sub>ja</sub> °C/W	l <sub>DR</sub> <sup>†</sup> (mA)	l <sub>DRM</sub> (A)
TO-92	-86	-0.6	0.74	125	170	-86	-0.6
TO-243AA (SOT-89)	-125	-1.2	1.6 <sup>±</sup>	15	78 <sup>‡</sup>	-125	-1.2

†

I<sub>D</sub> (continuous) is limited by max rated T<sub>j</sub>. Mounted on FR5 board, 25mm x 25mm x 1.57mm. ‡

#### Electrical Characteristics (T<sub>a</sub> = 25°C unless otherwise specified)

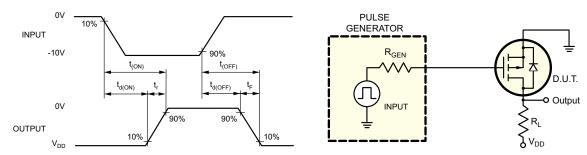
Sym	Parameter	Min	Тур	Мах	Units	Conditions			
BV <sub>DSS</sub>	Drain-to-source breakdown voltage	-400	-	-	V	V <sub>GS</sub> = 0V, I <sub>D</sub> = -2.0mA			
V <sub>GS(th)</sub>	Gate threshold voltage	-1.0	-	-2.4	V	$V_{GS} = V_{DS}, I_{D} = -1.0 \text{mA}$			
$\Delta V_{GS(th)}$	Change in $V_{GS(th)}$ with temperature	-	-	4.8	mV/ºC	$V_{GS} = V_{DS}, I_{D} = -1.0 \text{mA}$			
I <sub>GSS</sub>	Gate body leakage	-	-	-100	nA	$V_{_{\rm GS}}$ = ± 20V, $V_{_{\rm DS}}$ = 0V			
			-	-10	μA	$V_{GS}$ = 0V, $V_{DS}$ = Max Rating			
I <sub>DSS</sub>	Zero gate voltage drain current		-	-1.0	mA	$V_{DS} = 0.8$ Max Rating, $V_{GS} = 0V$ , $T_A = 125^{\circ}C$			
	On-state drain current	-0.2	-0.3	-	A	V <sub>GS</sub> = -4.5V, V <sub>DS</sub> = -25V			
D(ON)		-0.4	-1.1	-	~	V <sub>GS</sub> = -10V, V <sub>DS</sub> = -25V			
P	Static drain-to-source on-state resistance	-	20	30	Ω	V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -100mA			
R <sub>DS(ON)</sub>			19	25		V <sub>GS</sub> = -10V, I <sub>D</sub> = -100mA			
$\Delta R_{DS(ON)}$	Change in $R_{DS(ON)}$ with temperature	-	-	0.75	%/°C	V <sub>GS</sub> = -10V, I <sub>D</sub> = -100mA			
G <sub>FS</sub>	Forward transconductance	100	175	-	mmho	V <sub>DS</sub> = -25V, I <sub>D</sub> = -100mA			
C <sub>ISS</sub>	Input capacitance	-	60	125		V <sub>GS</sub> = 0V,			
C <sub>oss</sub>	Common source output capacitance	-	20	70	pF	$V_{DS}^{10} = -25V,$			
C <sub>RSS</sub>	Reverse transfer capacitance	-	10	25		f = 1.0 MHz			
t <sub>d(ON)</sub>	Turn-on delay time	-	-	10					
t	Rise time	-	-	10	20	$V_{DD} = -25V,$			
t <sub>d(OFF)</sub>	Turn-off delay time	-	-	20	ns	$I_{D} = -0.4A,$ $R_{GEN} = 25\Omega$			
t <sub>r</sub>	Fall time		-	13		GEN			
V <sub>SD</sub>	Diode forward voltage drop	-	-	-1.8	V	V <sub>GS</sub> = 0V, I <sub>SD</sub> = -100mA			
t <sub>rr</sub>	Reverse recovery time	-	300	-	ns	$V_{gs} = 0V, I_{sp} = -100mA$			

Notes:

All D.C. parameters 100% tested at 25°C unless otherwise stated. (Pulse test: 300µs pulse, 2% duty cycle.) 1.

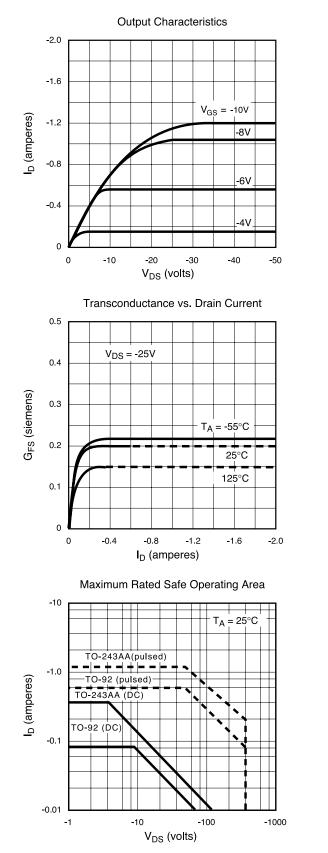
2. All A.C. parameters sample tested.

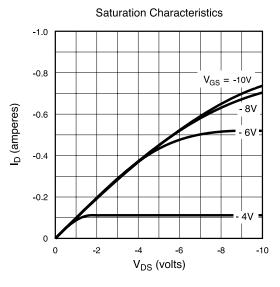
#### **Switching Waveforms and Test Circuit**



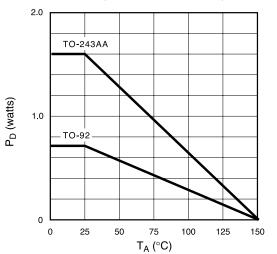
## **TP2540**

#### **Typical Performance Curves**

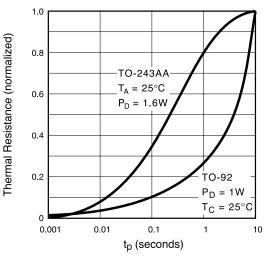




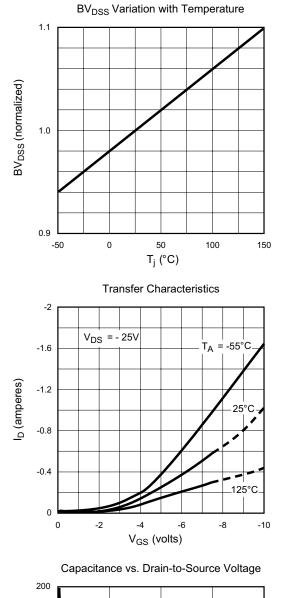
Power Dissipation vs. Ambient Temperature



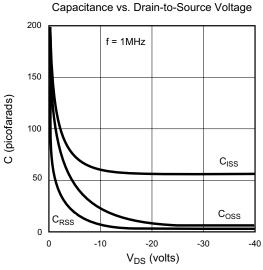
Thermal Response Characteristics

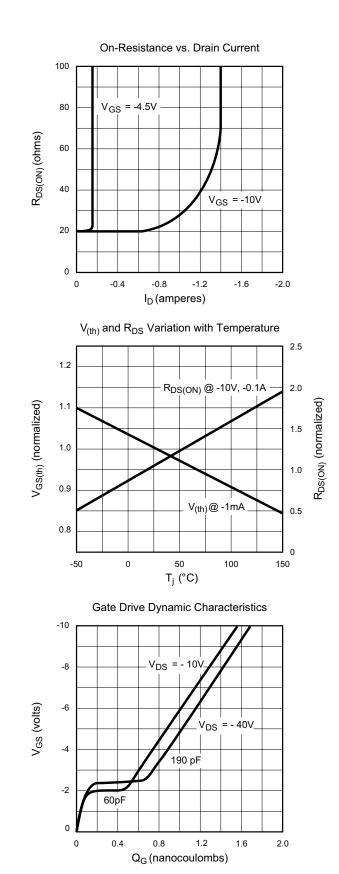


## **TP2540**



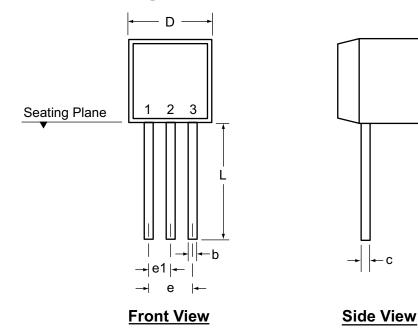
#### Typical Performance Curves (cont.)

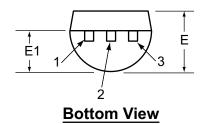




A

# 3-Lead TO-92 Package Outline (N3)





Symb	ol	Α	b	С	D	E	E1	e	e1	L
Dimensions (inches)	MIN	.170	.014†	.014 <sup>†</sup>	.175	.125	.080	.095	.045	.500
	NOM	-	-	-	-	-	-	-	-	-
	MAX	.210	.022†	.022†	.205	.165	.105	.105	.055	.610*

JEDEC Registration TO-92.

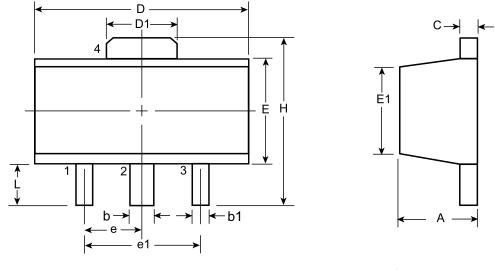
\* This dimension is not specified in the JEDEC drawing.

*†* This dimension differs from the JEDEC drawing.

Drawings not to scale.

Supertex Doc.#: DSPD-3TO92N3, Version E041009.

# 3-Lead TO-243AA (SOT-89) Package Outline (N8)



Top View

Side View

Symbo	ol	Α	b	b1	С	D	D1	Е	E1	е	e1	Н	L	
Dimensions (mm) MIN MAX	MIN	1.40	0.44	0.36	0.35	4.40	1.62	2.29	2.00†			3.94	0.89	
	NOM	-	-	-	-	-	-	-	-				-	-
	MAX	1.60	0.56	0.48	0.44	4.60	1.83	2.60	2.29		200	4.25	1.20	

JEDEC Registration TO-243, Variation AA, Issue C, July 1986.

*†* This dimension differs from the JEDEC drawing

Drawings not to scale.

Supertex Doc. #: DSPD-3TO243AAN8, Version E051509.

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to <u>http://www.supertex.com/packaging.html</u>.)

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